

AMENDMENTS TO THE SPECIFICATION

Please insert the following text immediately after Paragraph 0020:

-- Figure 8 shows schematically a flexible interconnect including heat sinks having fins.

Figure 9 shows schematically a flexible interconnect including heat sinks having heat pipes.

Figure 10 shows schematically a flexible interconnect including heat sinks having cooling coils as an active cooling mechanism. --

Please amend Paragraph 0029 to read as follows:

-- In one embodiment of the present invention, as shown in Figure 5, a heat sink 100 is attached to a surface of flexible interconnect structure 10, which surface is typically opposite to the surface on which circuit components and circuit traces are disposed. Each heat sink 100 covers a removed portion or hole (60, 64) formed in the flexible interconnect structure 10 and is typically attached thereto with an electrically insulating adhesive, such as an epoxy. Heat sink 100 comprises a thermally conductive material, such as metals or high-conductivity ceramics; preferably a metal having high thermal conductivity, such as silver, aluminum, or copper. The term "high-conductivity ceramic" means a ceramic having a thermal conductivity greater than about 100 W/m/K. Heat sink 100 may advantageously have a plurality of fins 102 extending away from the flexible interconnect structure 10 to promote rapid dissipation of heat. Alternatively, heat sink 100 is attached to flexible interconnect structure 10 to cover more than one removed portion or hole. In still another embodiment, a sheet of thermally conductive material is attached to flexible interconnect structure 10 to cover substantially its entire surface area. These alternative embodiments of heat sinks 100 provide larger surface areas for heat dissipation by convection. --

Please amend Paragraph 0030 to read as follows:

-- In one embodiment of the present invention, heat sink 100 can ~~comprises~~ comprise a mechanism for active cooling. Active cooling can remove heat faster than cooling that relies on natural convection. A mechanism for active cooling can include heat pipes 104, mechanism to effect refrigeration, or mechanism that effects heat transport by the Peltier effect. --